

ABSTRACT

The present invention provides a resin film-forming sheet to be stuck to a silicon wafer to form a resin film on the silicon wafer, wherein the surface roughness (Ra) of the surface (α) of the sheet on the side to be stuck to a silicon wafer is 40 nm or more. The resin film-forming sheet is excellent in reworkability. The invention also provides a resin film-forming composite sheet having such a configuration that the resin film-forming sheet is directly laminated on a support.